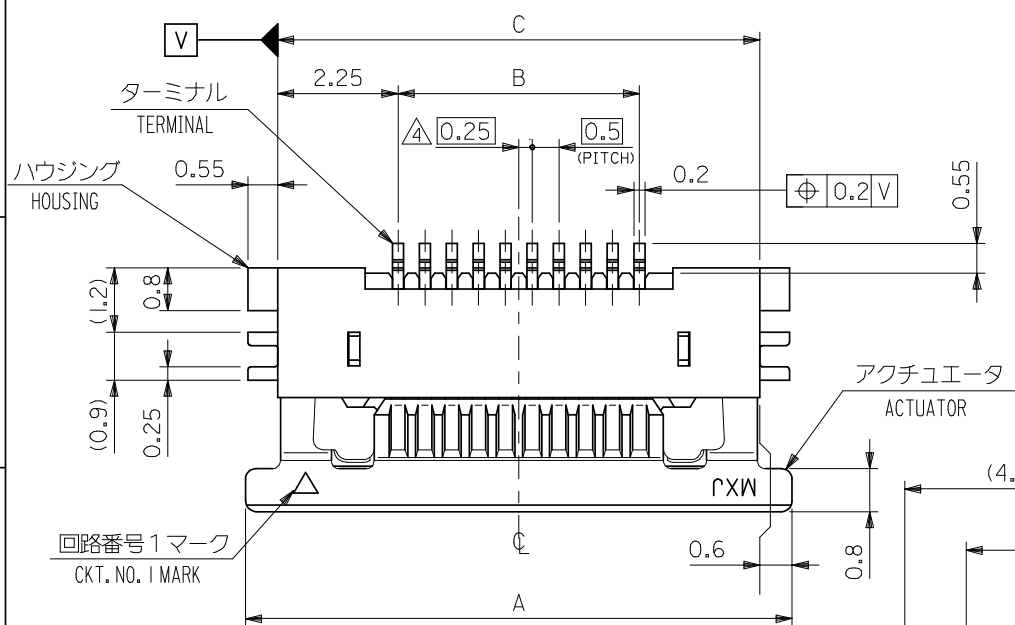
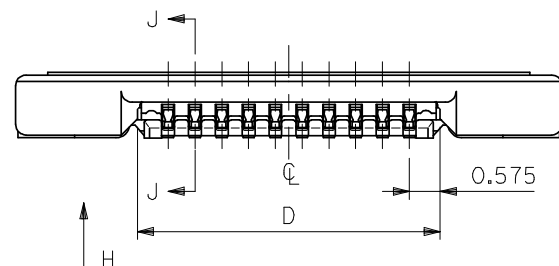
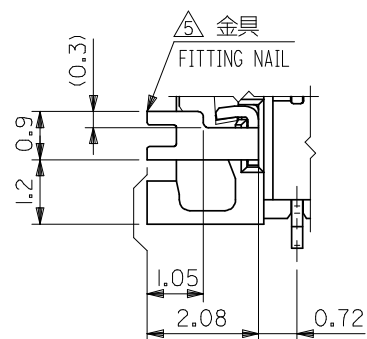
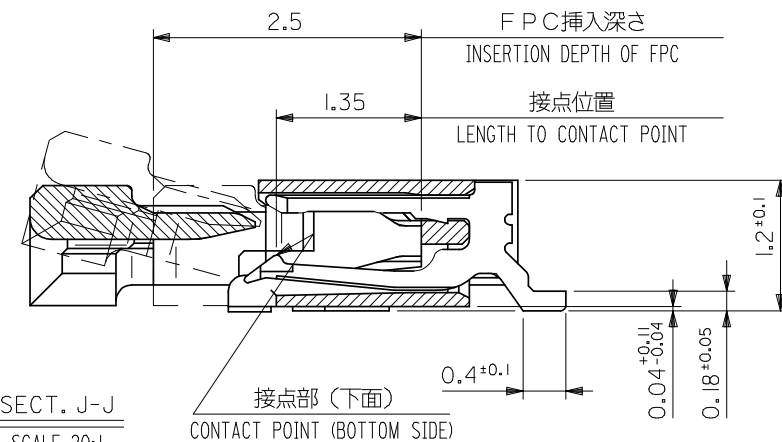




VIEW H



SECT. J-J
SCALE 20:1

D) I) D)	0.28 ±0.03	13.65	17	12.5	18.2	54548-2670	54548-26 19	26
	0.3 ±0.03	12.65	16	11.5	17.2	54548-2470	54548-24 19	24
		11.65	15	10.5	16.2	54548-2270	54548-22 19	22
		11.15	14.5	10	15.7	54548-2170	54548-21 19	21
		10.65	14	9.5	15.2	54548-2070	54548-20 19	20
		10.15	13.5	9	14.7	54548-1970	54548-19 19	19
		9.65	13	8.5	14.2	54548-1870	54548-18 19	18
		9.15	12.5	8	13.7	54548-1770	54548-17 19	17
		8.65	12	7.5	13.2	54548-1670	54548-16 19	16
		8.15	11.5	7	12.7	54548-1570	54548-15 19	15
		7.65	11	6.5	12.2	54548-1470	54548-14 19	14
		7.15	10.5	6	11.7	54548-1370	54548-13 19	13
		6.65	10	5.5	11.2	54548-1270	54548-12 19	12
		6.15	9.5	5	10.7	54548-1170	54548-11 19	11
		5.65	9	4.5	10.2	54548-1070	54548-10 19	10
		5.15	8.5	4	9.7	54548-0970	54548-09 19	9
		4.65	8	3.5	9.2	54548-0870	54548-08 19	8
		4.15	7.5	3	8.7	54548-0770	54548-07 19	7
		3.65	7	2.5	8.2	54548-0670	54548-06 19	6
		3.15	6.5	2	7.7	54548-0570	54548-05 19	5
2.65	6.0	1.5	7.2	54548-0470	54548-04 19	4		
THICKNESS OF FPC	D	C	B	A	EMBOSSD TAPE ORDER No. オーダー番号	製品番号 MATERIAL No.	極数 CIRCUIT	

REVISED	EC NO: J2008-4048	DRWN:MNABEI CH'KD:THARYAMA APPR:NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				10 UNDER	± 0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-			
				10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE 2004/01/09				
				30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2004/01/09	MOLEX MOLEX INCORPORATED			
				ANGULAR ±3 °	MATERIAL NO.		DOCUMENT NO. SD-54548-037				
REV			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

F

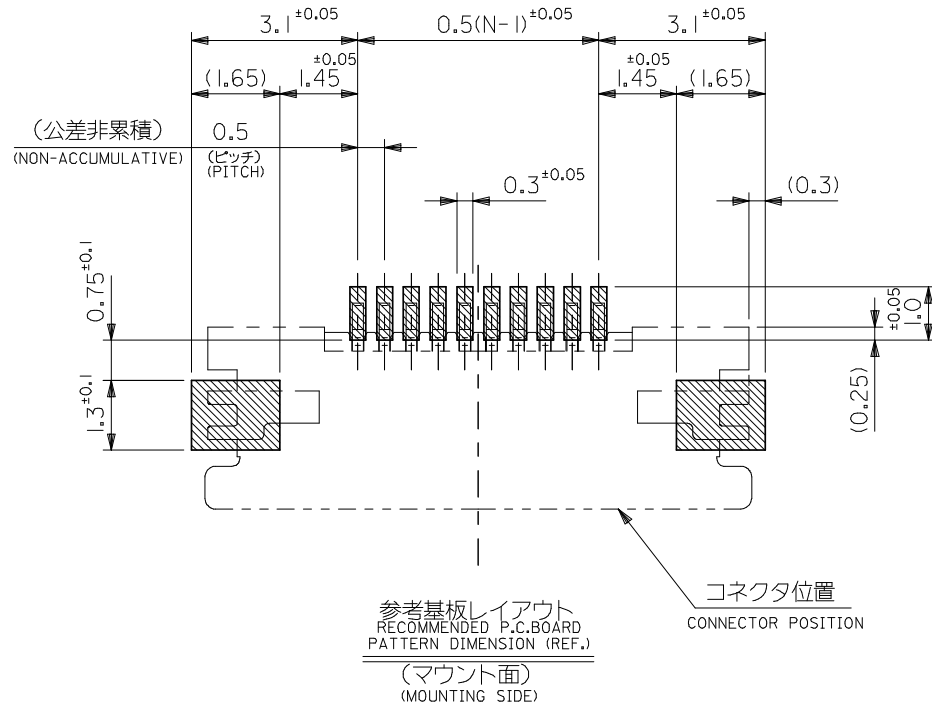
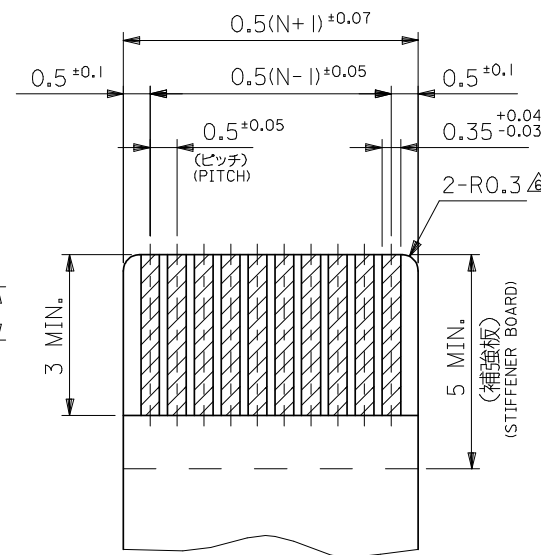
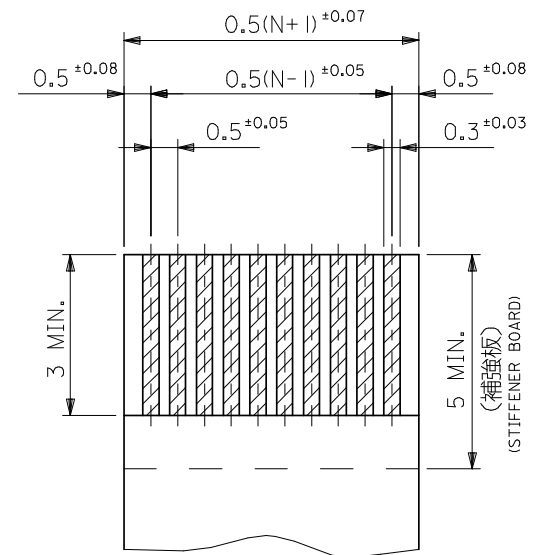
E

D

C

B

A



注記 NOTES

1. 使用材料 MATERIAL

ハウジング : LCP, UL94V-0
HOUSING

アクチュエータ : PPS, UL94V-0
ACTUATOR

ターミナル : リン青銅 (t=0.2)、ニッケル下地 鍍ビスマスマッキ
TERMINAL PHOSPHOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING.

金具 : リン青銅 (t=0.2)、ニッケル下地 鍍メッキ
FITTING NAIL PHOSPHOR BRONZE, PURE-TIN OVER NICKEL PLATING.

2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54548-**-19 SHOULD BE LOCKED.

△ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z
に対し上方向 0 MAX.、下方向 0.15 MAX. とし
相互のバツキ量は 0.1 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM Z
UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX.
OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.

△ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

△ パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.

△ R0.3はFPC導体部にかからないこと
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

7. N: 極数 N: CIRCUIT.

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。

導体部については軟銅箔35μmまたは50μmを推奨します。

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.

RECOMMENDED CONDUCTOR SPEC :

THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。

接着剤は熱硬化接着剤を推奨します。

尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC

RECOMMENDED MATERIAL/THICKNESS.

STIFFENER FILM : POLYIMIDE

BASE FILM THICKNESS : 25μm

BONDING AGENT : THERMOSETTING BONDING AGENT

PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT
AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN
ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE- MOLEX INCORPORATED			
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE 2004/01/09				
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2004/01/09				
		ANGULAR ± 3 °		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-54548-037		SHEET NO. 2 OF 2	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10

9

8

7

6

5

4

3

2

1

F

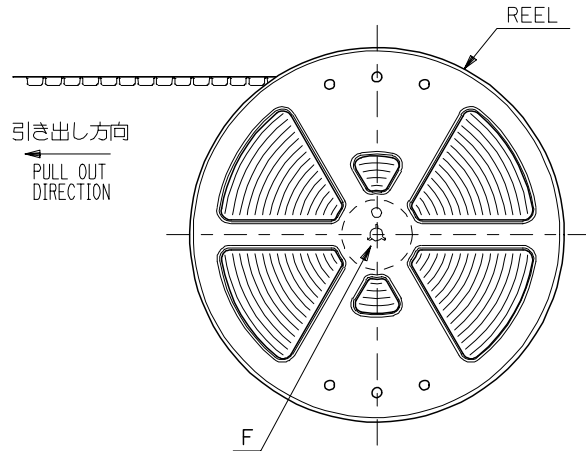
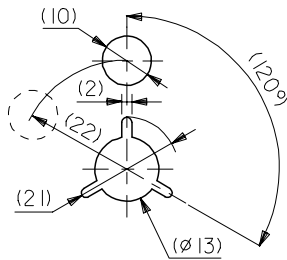
E

D

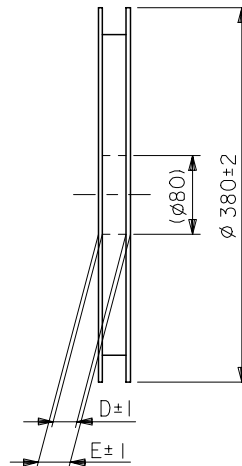
C

B

A

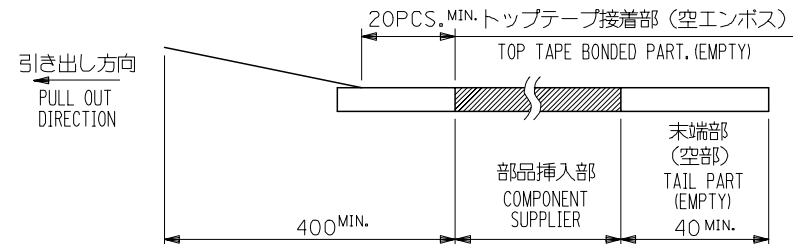


DETAIL F

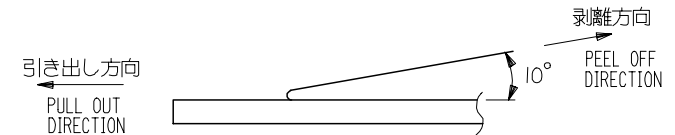


NOTES

- 製品詳細寸法については図面 SD-54548-037 を参照下さい。
RE DETAILED DIMENSION, SEE SD-54548-037.
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：0.1N ～ 1.3N { 10gf ～ 130gf }
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ～ 1.3N (10gf ～ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE)：PET , PE , PEF
リール(REEL)：ポリスチレン (P.S) <リサイクル材を含む>
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は54548-**-70の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54548-**-70.

REVISED	EC NO: J2005-2516 DRWN:WABEJ CHKD:KTOYODA APPR:NUKITA	2005/02/28 2005/02/28 2005/03/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				10 UNDER	±0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY -LEAD FREE-		
				10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/01/09			
				30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/01/09	MOLEX INCORPORATED		
				ANGULAR ±3 °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54548-038		
REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

9

8

7

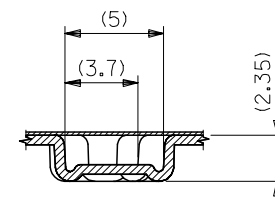
6

5

4

3

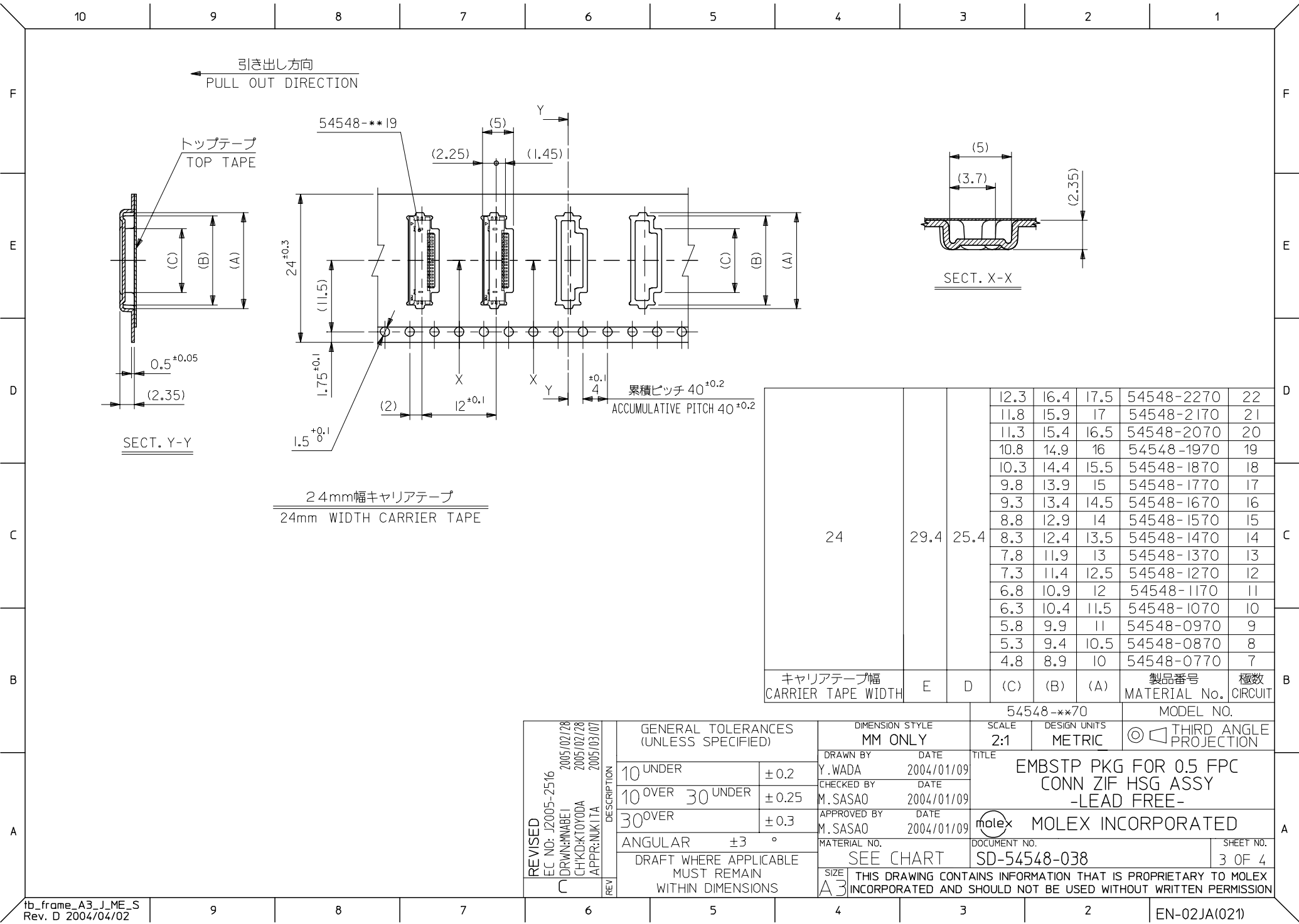
2



SECT. X-X

16	21.4	17.4	4.3	8.4	9.5	54548-0670	6
			3.8	7.9	9	54548-0570	5
			3.3	7.4	8.5	54548-0470	4
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	製品番号 MATERIAL No.	極数 CIRCUIT

REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE 2004/01/09					
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2004/01/09	molex MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54548-038		2 OF 4		
REV				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
EC NO: J2005-2516		2005/02/28		DRAWN:WABEI		2005/02/28		2005/03/07		
		CHK:KATOYODA		APPR:NUKIITA						



24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	29.4	25.4	12.3	16.4	17.5	54548-2270	22
			11.8	15.9	17	54548-2170	21
			11.3	15.4	16.5	54548-2070	20
			10.8	14.9	16	54548-1970	19
			10.3	14.4	15.5	54548-1870	18
			9.8	13.9	15	54548-1770	17
			9.3	13.4	14.5	54548-1670	16
			8.8	12.9	14	54548-1570	15
			8.3	12.4	13.5	54548-1470	14
			7.8	11.9	13	54548-1370	13
			7.3	11.4	12.5	54548-1270	12
			6.8	10.9	12	54548-1170	11
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	6.3	10.4	11.5	54548-1070	10
			5.8	9.9	11	54548-0970	9
			5.3	9.4	10.5	54548-0870	8
			4.8	8.9	10	54548-0770	7
			(C)	(B)	(A)	製品番号 MATERIAL No.	極数 CIRCUIT

REVISED EC NO: J2005-2516 2005/02/28 DRWN:MWABE1 CHKD:KTOYODA APPR:NUKITA 2005/03/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/01/09					
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/01/09	MOLEX MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54548-038		3 OF 4		
	REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

